



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SO-8					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	520	290 000	200 °C + N2	0	0
HAST	1904	276 500	130 °C, 85 % RH	0	0
Pressure Pot	1940	186 240	121°, 15 PSIG	0	0
Solder DUNK	564	1692	260 °C, 10 s	0	0
Solderability	105	690	883 M2003	0	0
Temp. Cycle	2422	2 306 500	-55 °C to 150 °C	0	0